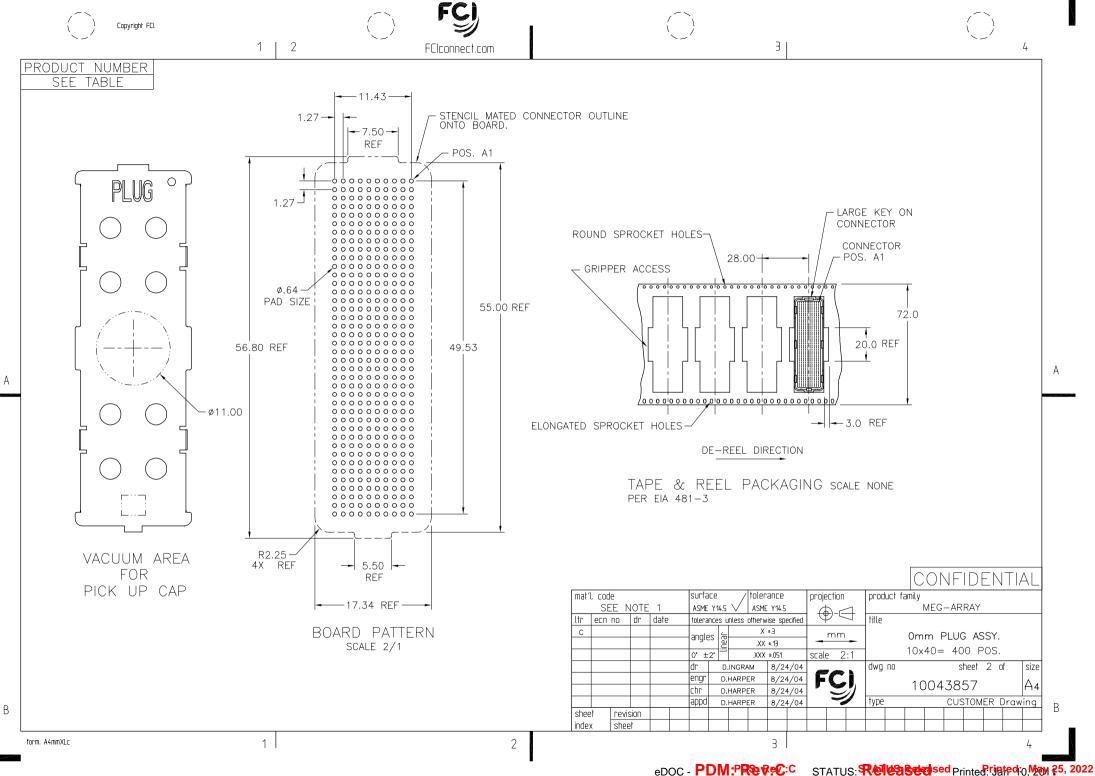


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		1 2	FCIconnect.com	
PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL	
10043857-102	VEC	30u"(0.76um) Au OVER Ni SEE MATED HEIGHT TABLE (BELOW) -	SnPb	
10043857-102LF	YES		SnAgCu LEAD FREE (6	50
10043857-202	XEC.		SnPb	
10043857-202LF	YES		SnAgCu LEAD FREE (6	57

. .

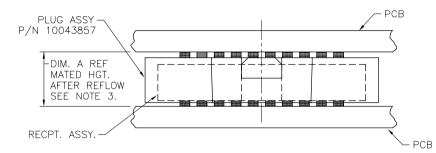
NOTES:

(1)

MAT'L: HOUSING: LCP CONTACT: COPPER ALLOY

PLATING:

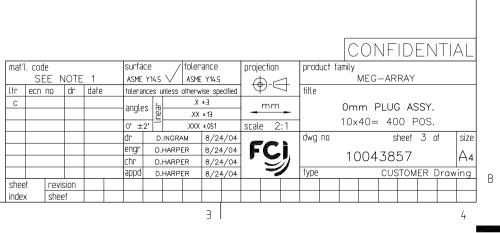
- CONTACT: (SEE TABLE ON SHEET3) SOLDER BALL: (SEE TABLE ON SHEET3) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Ag/0.5Cu
- (2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- (3.) MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- (4.) PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- (5.) PLATING FOR INDICATED -2XX SERIES PART NOS. IS AU OVER NI WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- (6) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (7.) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE				
DIM. A	RECPT. ASSY. P/N	-2XX PLATING		
4.0	74221	SEE NOTE 4		
6.0	74388	SEE NOTE 5		
8.0	74390	SEE NOTE 5		

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE



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